5V Dual Differential PECL to TTL Translator

The MC100ELT23 is a dual differential PECL to TTL translator. Because PECL (Positive ECL) levels are used, only +5 V and ground are required. The small outline 8-lead package and the dual gate design of the ELT23 makes it ideal for applications which require the translation of a clock and a data signal.

The PECL inputs are differential; therefore, the MC100ELT23 can accept any standard differential PECL input referenced from a V_{CC} of 5.0 V.

- 3.5 ns Typical Propagation Delay
- 24 mA TTL Outputs
- Flow Through Pinouts
- The 100 Series Contains Temperature Compensation
- Operating Range $V_{CC} = 4.75$ V to 5.25 V with GND = 0 V
- Internal Input 50 KΩ Pulldown Resistors
- Q Output Will Default LOW with Inputs Left Open or < 1.3 V

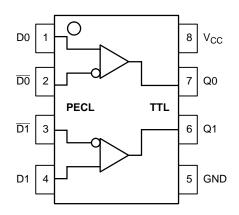


Figure 1. 8–Lead Pinout and Logic Diagram (Top View)

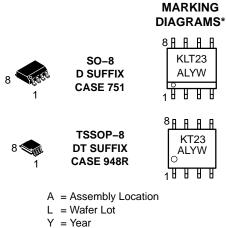
PIN DESCRIPTION

PIN	FUNCTION
Qn	TTL Outputs
Dn, <u>Dn</u>	PECL Differential Inputs
V _{CC}	Positive Supply
GND	Ground



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W = Work Week

*For additional marking information, see Application Note AND8002/D.

ORDERING INFORMATION

Device	Package	Shipping†
MC100ELT23D	SO-8	98 Units / Rail
MC100ELT23DR2	SO-8	2500 / Reel
MC100ELT23DT	TSSOP-8	98 Units / Rail
MC100ELT23DTR2	TSSOP-8	2500 / Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ATTRIBUTES

Characterist	Characteristics					
Internal Input Pulldown Resistor	50 kΩ					
Internal Input Pullup Resistor	N/A					
ESD Protection	Human Body Model Machine Model	> 2 KV > 400 V				
Moisture Sensitivity, Indefinite Time C	Out of Drypack (Note 1)	Level 1				
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V–0 @ 0.125 in				
Transistor Count		91				
Meets or exceeds JEDEC Spec EIA/J	IESD78 IC Latchup Test					

1. For additional information, see Application Note AND8003/D.

MAXIMUM RATINGS (Note 2)

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	Power Supply	GND = 0 V		7	V
VI	Input Voltage	GND = 0 V	$V_{I} \leq V_{CC}$	0 to 6	V
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 LFPM 500 LFPM	8 SOIC 8 SOIC	190 130	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	8 SOIC	41 to 44	°C/W
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 LFPM 500 LFPM	8 TSSOP 8 TSSOP	185 140	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	8 TSSOP	41 to 44 ± 5%	°C/W
T _{sol}	Wave Solder	< 2 to 3 sec @ 248°C		265	°C

2. Maximum Ratings are those values beyond which device damage may occur.

PECL INPUT DC CHARACTERISTICS V_{CC} = 5.0 V; GND = 0.0 V (Note 3)

		-40°C		25°C			85°C				
Symbol	Characteristic	Min	Тур	Мах	Min	Тур	Max	Min	Тур	Max	Unit
VIH	Input HIGH Voltage (Single–Ended) (Note 5)	3835		4120	3835		4120	3835		4120	mV
V _{IL}	Input LOW Voltage (Single–Ended)	3190		3525	3190		3525	3190		3525	mV
VIHCMR	Input HIGH Voltage Common Mode Range (Differential) (Note 4)	2.2		5.0	2.2		5.0	2.2		5.0	V
I _{IH}	Input HIGH Current			150			150			150	μΑ
IIL	Input LOW Current	0.5			0.5			0.5			μΑ

NOTE: Devices are designed to meet the DC specifications shown in the above table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained.

3. Input parameters vary 1:1 with V_{CC}. V_{CC} can vary \pm 0.25 V. 4. V_{IHCMR} min varies 1:1 with GND, V_{IHCMR} max varies 1:1 with V_{CC}. 5. TTL output R_L = 500 Ω to GND.

TTL OUTPUT DC CHARACTERISTICS V_{CC} = 4.75V to 5.25V; T_A = -40° C to 85°C

Symbol	Characteristic	Condition	Min	Тур	Max	Unit
V _{OH}	Output HIGH Voltage	I _{OH} = -3.0 mA	2.4		(Note 6)	V
V _{OL}	Output LOW Voltage	I _{OL} = 24 mA			0.5	V
I _{CCH}	Power Supply Current			23	33	mA
I _{CCL}	Power Supply Current			26	36	mA
I _{OS}	Output Short Circuit Current		-150		-60	mA

6. Max level is V_{CC} – 0.7 V by design.

AC CHARACTERISTICS V_{CC} = 5.0 V; GND= 0.0 V (Note 7 and Note 8)

		-40°C		25°C			85°C				
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{max}	Maximum Toggle Frequency					100					MHz
t _{JITTER}	Random Clock Jitter (RMS)					35					ps
t _{PLH}	Propagation Delay @ 1.5 V	2.0		5.5	2.0		5.5	2.0		5.5	ns
t _{PHL}	Propagation Delay @ 1.5 V	2.0		5.5	2.0		5.5	2.0		5.5	ns
V _{PP}	Input Swing (Note 9)	200		1000	200		1000	200		1000	mV
t _r /t _f	Output Rise Time (10–90%) Output Fall Time (10–90%)					1.6 1.1					ns ns

7. V_{CC} can vary ± 0.25 V. 8. TTL output $R_L = 500 \Omega$ to GND, and $C_L = 20$ pF to GND. Refer to Figure 2. 9. $V_{PP}(min)$ is the minimum input swing for which AC parameters are guaranteed. The device has a DC gain of ≈ 40 .

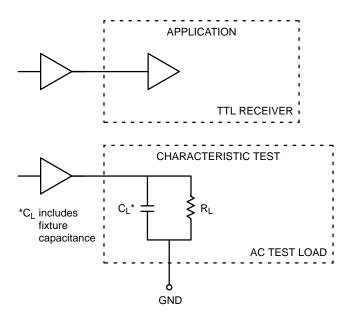


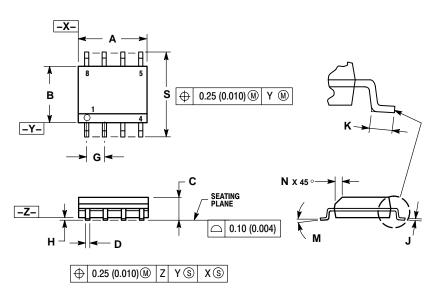
Figure 2. TTL Output Loading Used for Device Evaluation

Resource Reference of Application Notes

AN1404	_	ECLinPS Circuit Performance at Non–Standard V _{IH} Levels
AN1405	-	ECL Clock Distribution Techniques
AN1406	-	Designing with PECL (ECL at +5.0 V)
AN1503	-	ECLinPS I/O SPICE Modeling Kit
AN1504	-	Metastability and the ECLinPS Family
AN1560	-	Low Voltage ECLinPS SPICE Modeling Kit
AN1568	-	Interfacing Between LVDS and ECL
AN1596	-	ECLinPS Lite Translator ELT Family SPICE I/O Model Kit
AN1650	-	Using Wire–OR Ties in ECLinPS Designs
AN1672	-	The ECL Translator Guide
AND8001	-	Odd Number Counters Design
AND8002	-	Marking and Date Codes
AND8020	-	Termination of ECL Logic Devices
AND8090	_	AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

SO-8 **D SUFFIX** PLASTIC SOIC PACKAGE CASE 751-07 **ISSUE AA**



NOTES:

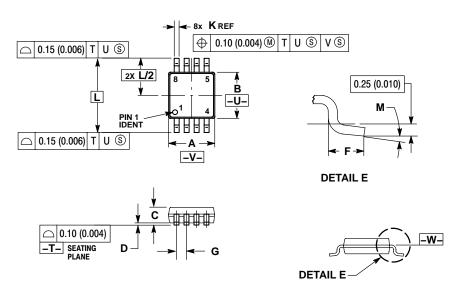
- VOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER. 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION. 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE

- A. MAXIMUM MOLD PROTRUSION 0.15 (0.000) FEM SIDE.
 DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D UMENSION AT MAXIMUM MATERIAL CONDITION.
 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

	MILLIN	IETERS	INC	HES		
DIM	MIN	MAX	MIN	MAX		
Α	4.80	5.00	0.189	0.197		
В	3.80	4.00	0.150	0.157		
C	1.35	1.75	0.053	0.069		
D	0.33	0.51	0.013	0.020		
G	1.27	7 BSC	0.050 BSC			
Н	0.10	0.25	0.004	0.010		
J	0.19	0.25	0.007	0.010		
K	0.40	1.27	0.016	0.050		
Μ	0 °	8 °	0 °	8 °		
N	0.25	0.50	0.010	0.020		
S	5.80	6.20	0.228	0.244		

PACKAGE DIMENSIONS

TSSOP-8 DT SUFFIX PLASTIC TSSOP PACKAGE CASE 948R-02 ISSUE A



NOTES:

- 1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.
- DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 TERMINAL NUMBERS ARE SHOWN FOR
- 6. DIMENSION A AND B ARE TO BE
- DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	2.90	3.10	0.114	0.122	
В	2.90	3.10	0.114	0.122	
C	0.80	1.10	0.031	0.043	
D	0.05	0.15	0.002	0.006	
F	0.40	0.70	0.016	0.028	
G	0.65	BSC	0.026	BSC	
K	0.25	0.40	0.010	0.016	
L	4.90	BSC	0.193	BSC	
М	0°	6 °	0 °	6 °	

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